



KERATHERM[®]

Thermal Management
Solutions





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KERAFOL®

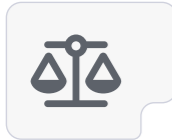
Your partner for Thermal Interface Materials and Technical Ceramic special thin- and thickfilm substrates, kiln furniture, wear protection substrates and customer specific development and services!



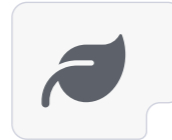
Quality Assurance



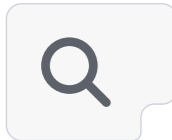
International Distribution Network



Optimum Price-Performance-Ratio



Environmental-Friendly



Research & Development



Future-Oriented

Modern production facilities

Our ceramic tapes are manufactured on the latest production facilities, either as standard or customer-specific products in a continuous process. The films can be ordered as endless, rolled material, or already individually punched in several thicknesses. Thereby the flexible ceramic films can be processed in customer specific geometries.

Development, quality control RoHS/Reach compliant

In order to offer our customers competent, customized advice and individual problem solutions, our engineers and staff are constantly doing research, development and tests on new, innovative and high quality materials in our inhouse R&D laboratory.

All KERATHERM® products are RoHS- and REACH compliant!



Many years of experience and a wide variety of innovative solutions makes KERAFOL® your essential partner in the field of "Thermal Management".

Experienced, innovative and customer-oriented

Many years of experience with oxidic and non-oxidic ceramic materials, continuous development of innovative and customer-focused solutions, and a global sales and distribution network with short delivery times are just some of the reasons why we are one of the leading specialists and manufacturers for thermal management solutions.

KERAFOL® – Customer satisfaction in all areas

KERAFOL® offers a wide range of products, suitable for diverse electronic and power electronic applications, as for example in the field of Automotive, energy, consumer electronic, power tools or industrial applications.

Thermal Management and KERATHERM®

Why “Thermal Solutions”?

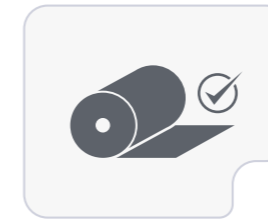
The continuously increasing technical demands, placed by the electronics industry on electronic and electrical devices, have led to a dramatic rise in the problem of heat generation. Higher frequencies, component miniaturization, enhanced functionality and increased device power ratings all lead to high temperatures that need to be controlled to ensure excellent long term stability and durability. Heat sinks, cooling plates and ventilators are often used to dissipate the heat and to reduce the temperature of the electrical circuits to a minimum.

The thermal coupling of suitable conducting materials is also gaining importance in this area. KERAFOL®, with its KERATHERM® products, offers an effective range of products for this purpose.

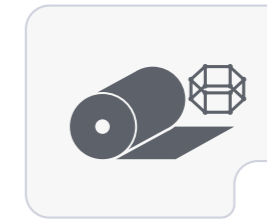
KERATHERM® are highly flexible products consisting of thermally conductive and electrically insulating polymers filled with either single or multi-component ceramic or thermally conductive materials. Possible mechanical reinforcements with glass fibers or other materials result in a product that is superior to conventional ceramic or mica discs.

KERATHERM® Products: Advantages and Properties

- High thermal conductivity
- High electrical isolation
- Very wide range of product categories like Tapes, Pads and liquid solutions
- Usage of different polymer base for individual needs
- Customized solutions possible
- 100 % Made in Germany



Thermal Conductive Tapes



Graphite Films



EMI-Absorber



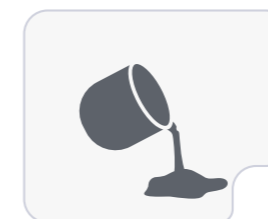
Thermal Adhesive



Thermal Grease



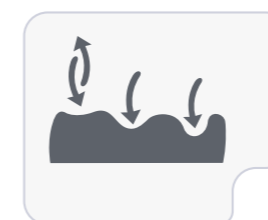
PCM



Gap Filler Liquids



Double sided Adhesive Films



Gap Pads

KERATHERM® Products

Gap Filler Liquids

Gap Filler Liquids are ceramic filled two-component elastomers without solvents, based on silicone or PU. The new product line of KERAFOF® product is characterized by its wide range of thermal conductivity, high degree of thermal insulation and its good rheological behavior. Due to the low viscosity, such Gap Filler Liquids are ideal for dispensing and even potting. Consequently, an installation with low mechanical stress can be realized, regardless of the tolerances and irregularity of the heat source/sink.



Thermal Adhesive

Two component liquid adhesive with high bond strength and room temperature curing. This silicone based elastomer combines a high thermal conductivity with a very good electrical isolation.



Gap Pads

SOFTTHERM® is the ideal material for smoothing out even large component irregularities. Thanks to its outstanding compressibility, it produces an optimum thermal contact combined with electrical insulation. The supplied thicknesses range from 0.5 - 5.0 mm. Other thicknesses on request.



Thermal Conductive Tapes

Thermal Conductive Tapes, silicone based and silicone free, have a smooth surface, in order to ensure that there is no entrapped air that would interfere with the heat transfer between the component and the heat sink. The material smoothes out microscopic irregularities in the contact surfaces, which improves the thermal interface and therefore increases the heat dissipation.



Adhesive Films

The Adhesive Films KL 90, KL 91 and KL 95 are thermoconducting, electrically insulating, double sided adhesive films. They have an excellent, permanent adhesive strength with high thermal conductivity and outstanding insulation characteristics at the same time.



Thermal Grease

Thermal Grease is especially characterized, by its good plasticity and very low thermal resistance. This non curing single component materials can be applied by dispensing or screen printing and achieves a very low bondline-thickness.



Graphite Films

Graphite Films are based on 100% pure graphite. The films are available as uncoated types or with filled adhesive or standard adhesives for specific applications.



PCM

Phase-Change-Material (PCM) is an excellent alternative for thermal pastes. The PCM changes its aggregate state from solid to liquid at a certain melting temperature. The result is a thermal interface material with a very low bond line. Furthermore the PCM compensates irregularities between the electronic component and the heat sink, thereby optimizing the contact between the surfaces and increasing the heat transfer.



EMI-Absorber

The new series KERABSORB is a hybrid material of THERMAL & EMI ABSORBER. This means, besides the classic properties of a Gap Pad (Softtherm Film) that is used between the heat source (electronic device) & heat sink, this new material also suppresses unwanted energy coupling, resonances or surface currents which cause board level EMI issues.



Gap Filler Liquids

	thermal conductivity	viscosity	dielectric breakdown voltage	density	hardness	characteristics	page
	W/mK	Pas	kV	g/cm ³	Shore 00		
GFL 3020	1.8	45 – 70	10.0	2.30	45 – 60	Gap Filler Liquids	16
GFL 3020 RF	2.0	45 – 85	10.0	2.40	45 – 60	Gap Filler Liquids	17
GFL 3030	3.0	90 – 140	6.0	2.94	65 – 85	Gap Filler Liquids	18
GFL 3035 ultracold	3.5	70 – 90	7.0	2.95	75 – 90	Gap Filler Liquids	19
GFL 3040	4.3	75 – 110	5.0	3.05	65 – 85	Gap Filler Liquids	20
GFL 3055	5.5	115 – 145	5.0	3.04	60 – 80	Gap Filler Liquids	21
GFL 1800 SL	1.8	2 – 8	7.5	2.30	55 – 75	Gap Filler Liquids	22
GFL 2400 SL	2.4	8 – 20	7.5	2.60	30 – 50	Gap Filler Liquids	23
GFL 3000 SL	2.8	10 – 30	6.0	2.77	55 – 75	Gap Filler Liquids	24

Gap Filler Liquids (silicone free)

	thermal conductivity	viscosity	dielectric breakdown voltage	density	hardness	characteristics	page
	W/mK	Pas	kV	g/cm ³	Shore 00		
GFU 15	1.5	140 – 180	8.0	2.30	65 – 85	Gap Filler Liquids	25

Thermal Conductive Tapes

	thermal conductivity	thermal resistance	dielectric breakdown voltage	hardness	characteristics	page
	W/mK	K/W	kV	Shore A		
L 86/50 KERATHERM® PEEK	1.1	0.51	8.0	70 – 80	high electrical isolation	47
86/37 KERATHERM® green	1.8	0.32	8.0	65 – 75	high insulation	45
86/25 KERATHERM® mint	2.5	0.225	3.5	60 – 75	high thermal conductivity	43
86/30 KERATHERM® white	2.5	0.22	1.5	70 – 80	high thermal conductivity	44
86/50 KERATHERM® pink	3.5	0.16	1.5	70 – 80	high thermal conductivity	46
86/60 KERATHERM® pink	4.5	0.14	5.0	45 – 60	high thermal conductivity, high insulation	48
86/82 KERATHERM® red	6.5	0.09	1.0	60 – 70	very high thermal conductivity	49

Thermal Conductive Tapes (silicone free)

	thermal conductivity	thermal resistance	dielectric breakdown voltage	hardness	characteristics	page
	W/mK	K/W	kV	Shore A		
U 80 silicone free	1.8	0.20	4.0	80 – 90	silicone free	50
U 85 silicone free	3.0	0.165	6.0	70 – 85	silicone free, high thermal conductivity and high insulation	51
U 90 silicone free	6.0	0.082	4.0	70 – 85	silicone free, high thermal conductivity	50

Gap Pads (SOFTTHERM® Films)

	thermal conductivity	thermal resistance	dielectric breakdown voltage	hardness	characteristics	page
	W/mK	K/W	kV	Shore 00		
86/125 SOFTTHERM® Film	1.5	1.6	6.0	10 – 25	soft, high compressibility	31
86/128 SOFTTHERM® Film	1.5	1.6	6.0	10 – 25	soft, high compressibility	31
86/225 SOFTTHERM® Film	2.0	1.2	6.0	30 – 45	fibreglass-reinforced, good self-w adhesive behavior on both sides	32
86/228 SOFTTHERM® Film	2.0	1.2	6.0	30 – 45	double layer	32
86/235 SOFTTHERM® Film	2.0	1.2	6.0	25 – 45	soft, high thermal conductivity	33
86/238 SOFTTHERM® Film	2.0	1.2	6.0	25 – 45	double layer	33
86/320 SOFTTHERM® Film	2.5	1.0	5.0	25 – 38	very soft, good dielectric properties	34
86/325 SOFTTHERM® Film	3.0	0.82	6.0	35 – 50	soft, high thermal conductivity	35
POLARIS 3000 SOFTTHERM® Film	3.0	0.82	7.0	50 – 80	extreme temperature stable	36
3500 SOFTTHERM® Film	3.5	0.73	5.0	45 – 65	soft, very good thermal and dielectric properties	37
86/450 SOFTTHERM® Film	4.5	0.54	5.0	65 – 75	very good thermal and dielectric properties	38
86/525 SOFTTHERM® Film	5.5	0.44	1.25	50 – 65	high thermal conductivity, very good compressibility	39
6000 SOFTTHERM® Film	6.0	0.41	4.0	55 – 75	high thermal conductivity	40

Gap Pads (silicone free)

	thermal conductivity	thermal resistance	dielectric breakdown voltage	hardness	characteristics	page
	W/mK	K/W	kV	Shore 00		
U 110 SOFTTHERM® Film (silicone free)	2.0	1.2	8.0	60 – 75	elastic, silicone free	41

Graphite Films

	thermal conductivity	thermal resistance	dielectric breakdown voltage	measured thickness	hardness	characteristics	page
	W/mK	K/W	kV	mm	Shore D		
S 900 highly compressed Graphite film	7.5	0.08	non isolating	0.290	25 – 35	high thermal conductivity	58

Thermal Adhesive

	thermal conductivity	viscosity	dielectric breakdown voltage	density	hardness	characteristics	page
	W/mK	Pas	kV	g/cm ³	Shore A		
KERATHERM® Bond 100 RT	1.5	40 – 70	6.0	2.1	20 – 35	Thermal Adhesive	26

Kerabsorb

	thermal conductivity	EMI Attenuation	dielectric breakdown voltage	measured thickness	hardness	page
	W/mK	dB	kV	mm	Shore 00	
Kerabsorb 1500 EMI Absorber	1.5	≥40	5.0	1.0	35 – 45	60
Kerabsorb 2500 EMI Absorber	2.5	≥40	5.0	1.0	35 – 50	60

Adhesive Films

	thermal conductivity	thermal resistance	dielectric breakdown voltage	hardness	characteristics	page
	W/mK	K/W	kV	Shore A		
KL 95 thermal conductive, adhesive film without fibreglass	1.30	0.32	2.0	60	thermal conductivity insulating adhesive	52
KL 91 thermal conductive, adhesive film with fibreglass	1.35	0.55	6.0	59	thermal conductivity insulating adhesive	53
KL 90 thermal conductive, adhesive film without fibreglass	1.40	0.52	6.0	45	thermal conductivity insulating adhesive	53

Thermal Grease

	DeltaT	measured thickness	characteristics	page
	°C	mm		
KP 12 silicone free thermal compound	≤1.2	0.025	silicone free	56
KP 14 silicone free thermal compound	≤1.2	0.025	silicone free	56
KP 97 ceramic filled silicone component	≤1.6	0.025	silicone based	56
KP 98 ceramic filled silicone component	≤1.4	0.025	silicone based, low thermal resistance	56
KP 99 ceramic filled silicone component	≤1.2	0.025	very low thermal resistance	56
KP 100 ceramic filled silicone component	≤1.6	0.025	high cycle resistance	57

PCM

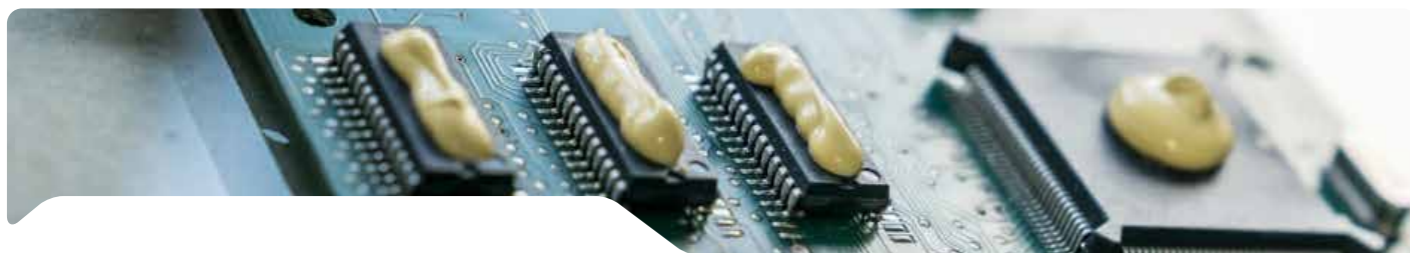
	thermal conductivity	Operating temperature	Softening interval	Possible layer thickness	Post-curing time (40°C @ 250 µm)	page
	W/mK	°C	°C	µm	h	
PCM 16125c phase change material	>3.5	-40 to +120	52 – 54	50 – 250	18 – 24	59



Thermal Management Challenges for electric vehicles

The change to electric powertrains and the increasing importance of autonomous driving imply a variety of new challenges. Thermal management or rather thermal connectivity and cooling of electrical components have an important

role to play. While there is a large number of Thermal Interface Materials, the most common solution for the automotive sector are the Gap Filler Liquids (GFL) and the SOFTTHERM® Pads.



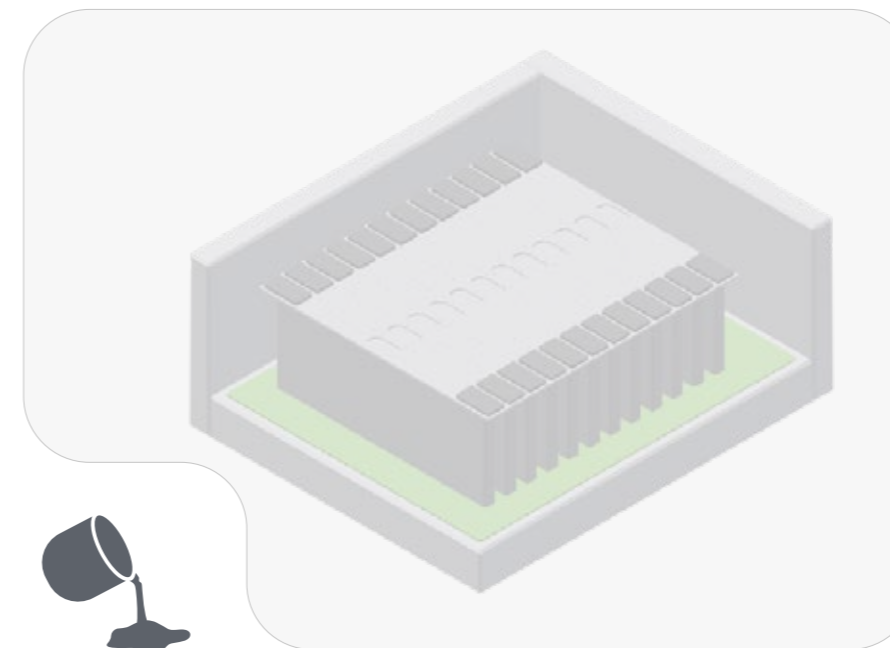
The switch to electric vehicles and the increasing importance of autonomous driving presents completely new applications and challenges in the area of "thermal management". The functional relationship between the operating temperature of a battery stack and its maximum achievable number of cycles has been proven. According to the literature, the following rule of thumb applies:

"Lowering the operating temperature by just 10°C can double the service life of battery cells".

The net reach of an electric car is also dependent on the operating temperature of the battery and thus also indirectly on the present thermal cooling. In addition to the concept for thermal connectivity of the energy source, the "car of tomorrow" also requires solutions for electrical components in the areas of LED, sensor technology, on-board network and inverter, one of the core elements of the electric powertrain.



Optimized thermal management for **e-mobility** and performance electronics through - Gap Filler "Liquids".



used in...



Airplanes



Electrical Cars



Multi-media



Cell phones



Power tools

The use of thermal pad setups in **e-mobility** is quite common.

Additionally, KERAFOLE® also offers Gap Filler Liquids as an alternative to conventional heat conductive Gap Pads. The soft and elastic Gap Filler Liquids are dispensable and quite easy to process.

GFL 3020 Gap Filler Liquid

Benefits

- Room temperature curing
- Easy to process and dispense
- High material utilization
- Very soft and elastic
- Very good price performance ratio



Properties	Unit	GFL 3020
Colour		yellow
Basic material		silicone
Mixing ratio		1:1
Curing		1h; RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.4
Thermal conductivity λ	W/mK	1.8
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	10.0
Mechanical Properties		
Hardness	Shore 00	45-60
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.30
Viscosity	Pas	45-70
Total mass loss (TML)	Ma. -%	0.19
Flame rating	UL-94	V-0
Possible thickness	mm	0.05-5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

GFL 3020 RF Gap Filler Liquid

Benefits

- Room temperature curing
- Easy to process and dispense
- High material utilization
- Very soft and elastic
- Very good price performance ratio



Properties	Unit	GFL 3020 RF
Colour		yellow
Basic material		silicone
Mixing ratio		1:1
Curing		1h; RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.2
Thermal conductivity λ	W/mK	2.0
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	10.0
Mechanical Properties		
Hardness	Shore 00	45-60
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.40
Viscosity	Pas	45-85
Total mass loss (TML)	Ma. -%	0.19
Flame rating	UL-94	V-0
Possible thickness	mm	0.1-5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

GFL 3030

Gap Filler Liquid

Benefits

- Room temperature curing
- Very high thermal performance
- Highly thixotropic
- High material utilization



Properties	Unit	GFL 3030
Colour		green
Basic material		silicone
Mixing ratio		1:1
Curing		1h; RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.82
Thermal conductivity λ	W/mK	3.0
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0
Mechanical Properties		
Hardness	Shore 00	65 - 85
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.94
Viscosity	Pas	90 - 140
Total mass loss (TML)	Ma. -%	< 0.06
Flame rating	UL-94	V - 0
Possible thickness	mm	0.2 - 5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

GFL 3035 ULTRACOLD

Gap Filler Liquid

PRELIMINARY DATA SHEET

Benefits

- Good thermal conductivity
- Good electrical insulation
- Room temperature curing
- Operating range starting from -90°C
- Highly thixotropic



Properties	Unit	GFL 3035 ULTRACOLD
Colour		olive
Basic material		silicone
Mixing ratio		1:1
Curing	°C	1h; RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	0,71
Thermal conductivity λ	W/mK	3.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	7.0
Mechanical Properties		
Hardness	Shore 00	75 - 90
Physical Properties		
Application temperature	°C	-90 to +200
Density	g/cm ³	2,95
Viscosity	Pas	70 - 90
Total mass loss (tbd)	Ma. -%	tbd
Flame rating	UL-94	V - 0 (self-test)
Possible thickness	mm	0.2 - 5.0

* Measured @ thickness 1mm ** Measured @ thickness 0.5 mm

GFL 3040

Gap Filler Liquid

Benefits

- Room temperature curing
- Very high thermal performance
- Highly thixotropic
- High material utilization



Properties	Unit	GFL 3040
Colour		lilac
Basic material		silicone
Mixing ratio		1:1
Curing		1h; RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.58
Thermal conductivity λ	W/mK	4.3
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	5.0
Mechanical Properties		
Hardness	Shore 00	65 - 85
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	3.05
Viscosity	Pas	75 - 110
Total mass loss (TML)	Ma. -%	<0.09
Flame rating	UL-94	V-0
Possible thickness	mm	0.2 - 5.0

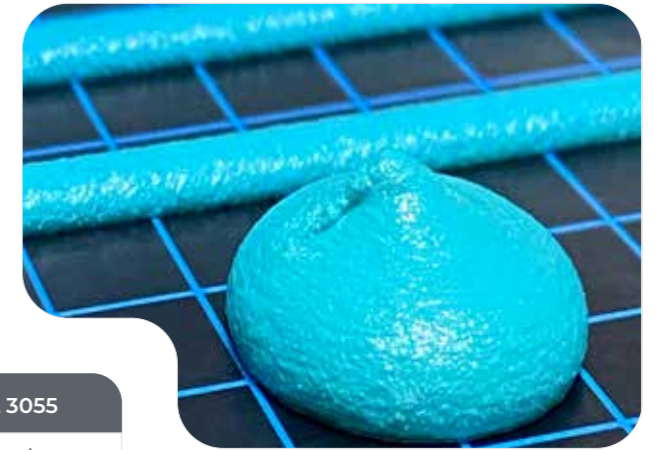
* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

GFL 3055

Gap Filler Liquid

Benefits

- Room temperature curing
- Very high thermal performance
- Highly thixotropic
- High material utilization



Properties	Unit	GFL 3055
Colour		turquoise
Basic material		silicone
Mixing ratio		1:1
Curing	°C	1h; RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	0,45
Thermal conductivity λ	W/mK	5,5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	5
Mechanical Properties		
Hardness	Shore 00	60 - 80
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	3,04 g/cm ³
Viscosity	Pas	115 - 145
Total mass loss (tbd)	Ma. -%	tbd
Flame rating	UL-94	V-0 (self-test)
Possible thickness	mm	0.2 - 5.0

* Measured @ thickness 1mm ** Measured @ thickness 0.5 mm

PRELIMINARY DATA SHEET

GFL 1800 SL Gap Filler Liquid

Benefits

- Room temperature curing
- Higher thermal conductivity in comparison to potting material
- Usage for Encapsulation, electromagnetic coils and applications with small fabrication tolerances
- Low Viscosity Gap Filler Liquid



Properties	Unit	GFL 1800 SL
Colour		green, white
Basic material		silicone
Mixing ratio		1:1
Curing	°C	1h ; 25 °C
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.38
Thermal conductivity λ	W/mK	1.8
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	7.5
Mechanical Properties		
Hardness	Shore 00	55 - 75
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.3
Viscosity	Pas	2 - 8
Total mass loss (TML)	Ma. -%	< 0.17
Flame rating	UL-94	V-0
Possible thickness	mm	0.2-5.0

* Measured @ thickness 1mm ** Measured @ thickness 0.5 mm

GFL 2400 SL Gap Filler Liquid

Benefits

- Room temperature curing
- Higher thermal conductivity in comparison to potting material
- Usage for Encapsulation, electromagnetic coils and applications with small fabrication tolerances
- Low Viscosity Gap Filler Liquid



Properties	Unit	GFL 2400 SL
Colour		green, blue
Basic material		silicone
Mixing ratio		1:1
Curing	°C	90-135 min; 25 °C
Thermal Properties*		
Thermal resistance R_{th}	K/W	< 1.02
Thermal conductivity λ	W/mK	> 2.4
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	> 7.5
Mechanical Properties		
Hardness	Shore 00	30 - 50
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.6
Viscosity	Pas	8 - 20
Total mass loss (TML)	Ma. -%	tbd
Flame rating	UL-94	V-0 (self-test)
Possible thickness	mm	0.2-5.0

* Measured @ thickness 1mm ** Measured @ thickness 0.5 mm

GFL 3000 SL Gap Filler Liquid

NEW PRELIMINARY DATA SHEET

Benefits

- Room temperature curing
- Higher thermal conductivity in comparison to potting material
- Usage for Encapsulation, electromagnetic coils and applications with small fabrication tolerances
- High thermal performance
- Low Viscosity Gap Filler Liquid



Properties	Unit	GFL 3000 SL
Colour		steelblue
Basic material		silicone
Mixing ratio		1:1
Curing	°C	1h ; 25 °C
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.90
Thermal conductivity λ	W/mK	2.8
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	6
Mechanical Properties		
Hardness	Shore 00	15-45
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.77
Viscosity	Pas	20-50
Total mass loss (TML)	Ma. -%	< 0.17
Possible thickness	mm	0.2-5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

GFU 15 silicone free Gap Filler Liquid

Benefits

- Room temperature curing
- Liquid assembly
- silicone free
- Contains no diisocyanate
- 1:1 Mixing ratio



Properties	Unit	GFU 15
Colour		orange
Basic material		silicone free
Mixing ratio		1:1
Curing at room temperature	h	< 24 RT
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.6
Thermal conductivity λ	W/mK	1.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	8.0
Mechanical Properties		
Hardness	Shore 00	65-85
Physical Properties		
Application temperature***	°C	-40 to +110
Density	g/cm ³	2.30
Viscosity A Comp.	Pas	140-180
Viscosity B Comp.	Pas	140-180
Possible thickness	mm	0.2-3.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm *** may increase in hardness

Gap Filler Liquids

Kerafol offers dispensing tests in our in-house laboratory. For further information please contact our application engineering team.

Benefits

- High temperature stability
- High thermal performance
- High dielectric strength
- Compensation of tolerances
- Balancing of vibrations and thermal expansions (CTE)
- Cycle resistant

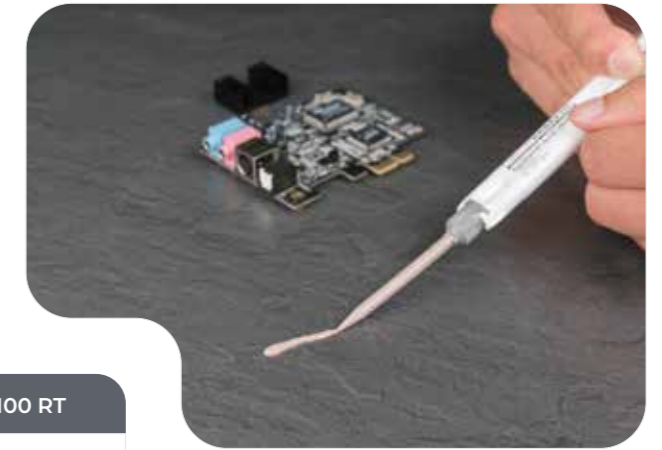


KERATHERM® Bond 100 RT

KERATHERM® Thermal Adhesives

Benefits

- High bond strength
- Room temperature curing
- Thixotropic and filling surface structures
- Very soft to compensate mechanical impacts like vibrations



Properties	Unit	100 RT
Colour		brown
Mixing ratio		1:1
Curing	°C	20 min RT
Thermal conductivity λ^*	W/mK	1.5
Thermal resistance R_{th}	K/W	1.66
Hardness	Shore A	20 - 35
Lap shear strength****	MPa	>15
Dielectric breakdown voltage $U_{d, AC}^{**}$	kV	6.0
Density	g/cm ³	2.1
Viscosity***	Pas	40 - 70
Application temperature	°C	-40 to +180

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm *** Shear rate 4.6s⁻¹ / 25°C **** Surface 25x25mm | 0,5mm thickness | (Alu / Alu)

Application Notes

- All surfaces should be even and free from oil, grease or dust. Clean surface with a solvent (e.g. acetone, thinner, etc.).
- Screw emulsion tube onto the cartridge.
- Squeeze adhesive out of the emulsion tube (in a strand of ca. 3 cm), until the adhesive emitted is of consistent light brown colour. Adhesive that is not of consistent colour will not bind and is thus to be disposed of.
- Evenly spread the adhesive on one of the surfaces to be bonded.
- Bond the components.
- Briefly press the components onto each other and avoid moving them for the next 30 minutes. If bonded at an angle or overhead, please secure the components.
- The initial hardness is achieved after 15 minutes, final hardness is achieved after four hours.

Packing units:

- Syringe: 5 ml
- Double cartridge: 50 ml & 400 ml
- Hobcock set with 34,5 kg per component

Special packing on request!

Application service

Dispensing service

KERAFOL® is using a professional cnc-controlled dispensing system in-house, which is available for trials under the guidance of an expert. Here, customized trial setups can be dispensed and assembled directly on site, perfect for trial setups in the sampling phase. This gives a first preview of the parameters for your serial process (cycle times, dispensing quantity, etc.).

The advantage of such a service is that an automated process with high repeatability and dosing accuracy can be simulated, which is not the case with a „test dosing“ by hand (human factor). The gap filler for the tests is always fresh and perfectly homogenized, which is often not the case with sample cartridges (especially if stored incorrectly).

Screen-Printing service

To apply Thermal Greases or liquid Phase Change Materials (PCM) in a precise way, KERAFOL® also provides a service for screen printing. In terms of PCMs, the materials are heated up to reach a certain flowing behaviour and afterwards they get applied by an individual screen to ensure the requested final thickness. For thermal greases, KERAFOL® is also able to apply the material by a special screen-printing process on both sides of the final product.

Possible applications are covering of electronic components like thyristors or the connection of semiconductors on ceramic or metal plates.

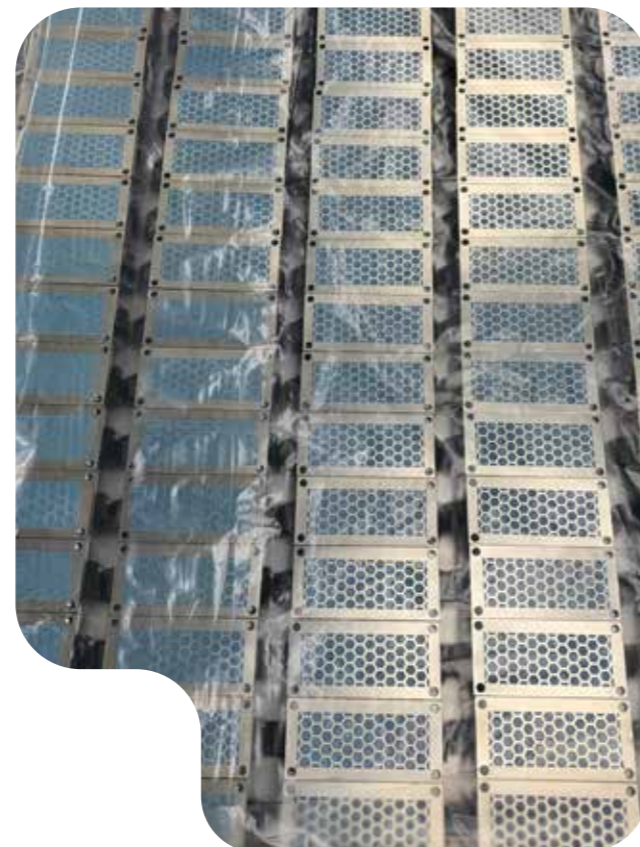
The service last from Prototypes to serial production.

Preparation for the test

- Kick-off-meeting with project presentation
- Send required parts in advance (equipment setup)
- Specification of cycle times / gap
- dimensions/dosing volumes (if required)
- Specification of special requirements (if requested)

Have we aroused your interest?

Request an appointment at:
keratherm@kerafol.com

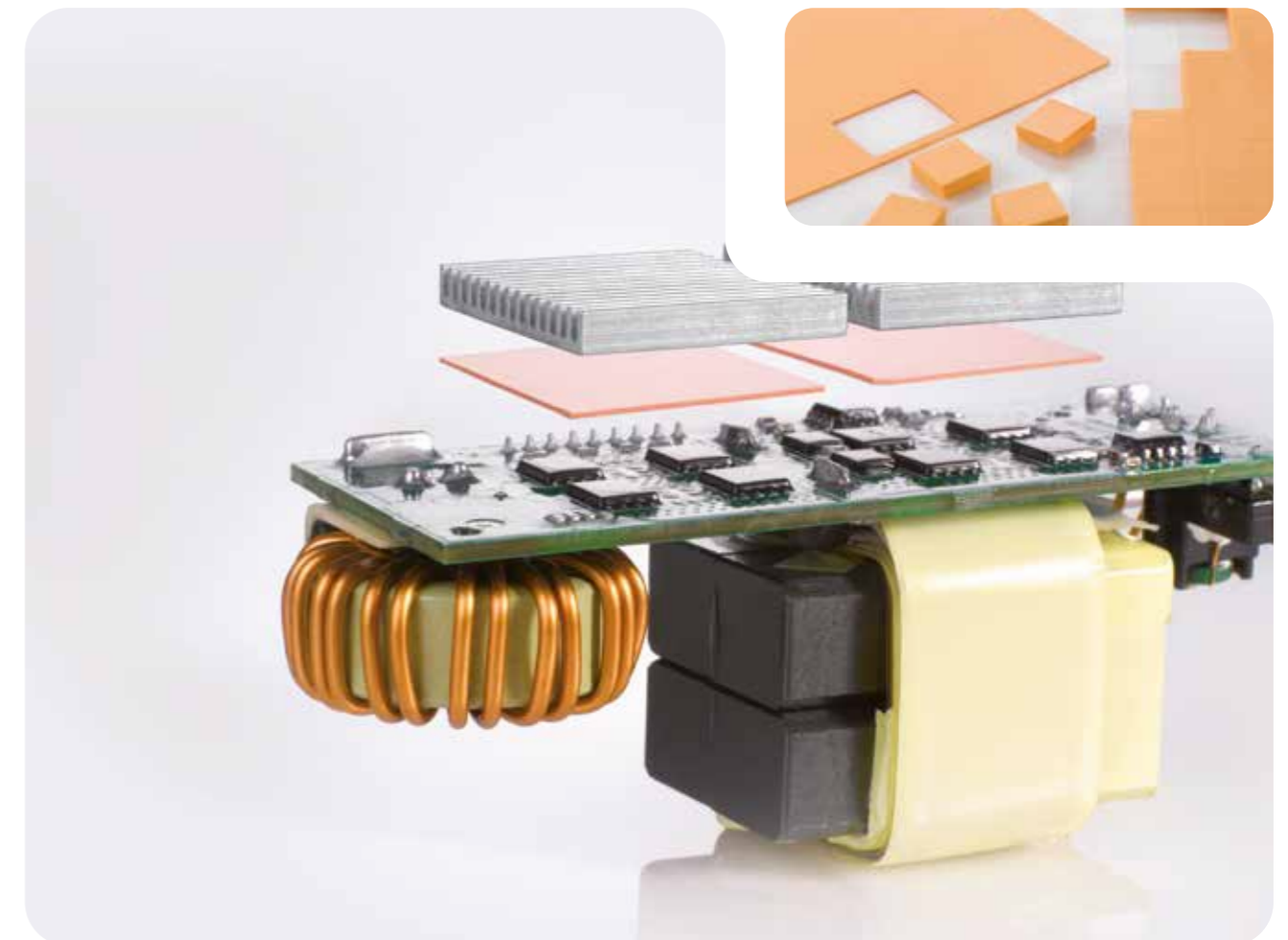


Gap Pads (SOFTTHERM® Films)

Gap Pads (SOFTTHERM® films) are highly thermally conductive and electrically insulating elastomers based on silicone or polyurethane.

Their softness and elasticity make them ideal for compensating even large unevennesses and air gaps between electronic components and heat sinks, thus enabling efficient heat transfer. In addition to different thermal conductivity and insulation classes, the gap pads differ in their feel.

Two-layer gap pads with additional protective layer or special adhesive coatings are also possible in principle. Depending on customer requirements, gap pads in various thicknesses (0.5 mm to 5.0 mm) can also be manufactured on request.



Benefits

- Industrial applications of components
- Compensation of component unevenness
- High thermal conductivity and electrical isolation
- Good compression behaviour
- Balancing of vibrations and thermal expansions (CTE)
- Easy handling and good mechanical stability

Applications

- Power electronics
- Power Tools
- Automotive
- Energy storage and converter
- Plasma supply panels

Film Options

- Different options in terms of mechanical strength (fiber glass) and adhesion level
- Single-sided adhesive coating possible
- Can be supplied as sheets or die-cut part

Properties

- High elastic behaviour
- Graduated thermal conductivity
- Good electrical insulation
- High temperature stability

used in...



Airplanes



Electrical Cars



Multi-media



Cell phones

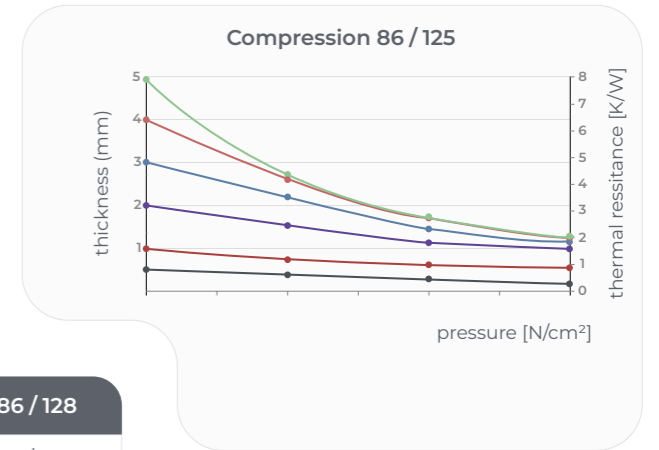


Power tools

86 / 125 & 86 / 128 Silicone Gap Pad

Benefits

- Low cost solution
- Very low Hardness
- Elastic behavior
- Also available as a double layer material



Properties	Unit	86 / 125	86 / 128
Colour		dark orange	pink / dark orange
Assembly		single layer, fibre glass reinforcement up to 4.0 mm	double layer carrier film 86/52 in 0.125 mm
Thermal Properties*			
Thermal resistance R_{th}	K/W	1.6	1.6
Thermal conductivity λ	W/mK	1.5	1.5
Electrical Properties**			
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0	6.0
Volume resistivity	Ωm	6.1×10^{10}	1.8×10^{12}
Dielectric loss factor $\tan \delta$		1.5×10^{-1}	1.0×10^{-3}
Dielectric constant ϵ_r		4.3	2.3
Mechanical Properties			
Hardness	Shore 00	10-25	10-25
Young's modulus	N/cm ²	24	67
Physical Properties			
Application temperature	°C	-40 to +180	-40 to +180
Density	g/cm ³	2.0	1.9
Total mass loss (TML)	Ma.-%	< 0.29	< 0.29
Flame rating	UL-94	V-0	V-0
Possible thickness	mm	0.5-5.0	0.5-5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm



! At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

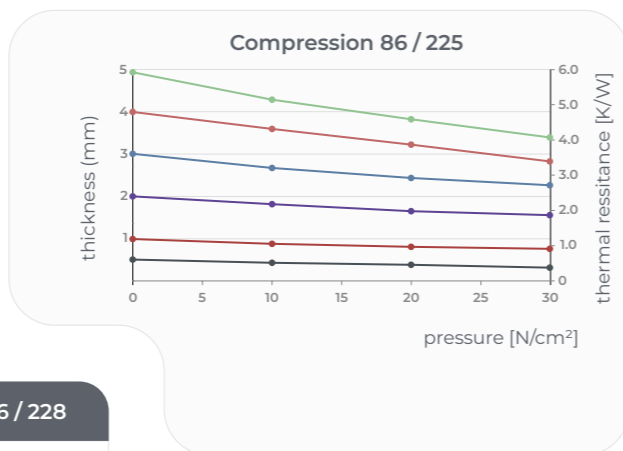
! Attention

At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

86 / 225 & 86 / 228 Silicone Gap Pad

Benefits

- Good price performance ratio
- Very soft to compensate mechanical impacts like vibrations
- Elastic behavior
- Also available as a double layer material

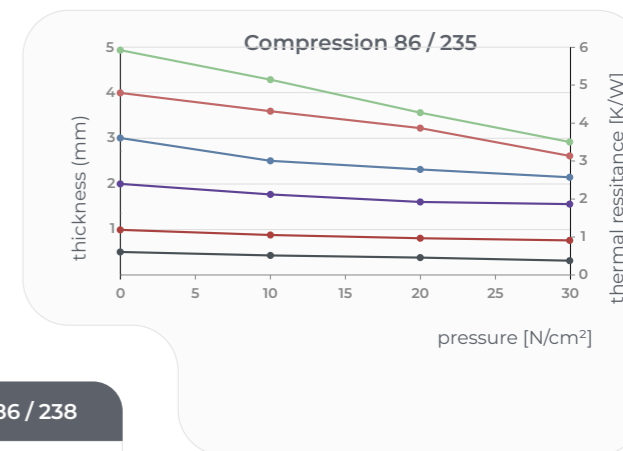


! At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

86 / 235 & 86 / 238 Silicone Gap Pad

Benefits

- low TML
- Very soft to compensate mechanical impacts like vibrations
- Elastic behavior
- Also available as a double layer material



! At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

Properties	Unit	86 / 225	86 / 228
Colour		orange	pink / orange
Assembly		single layer, fibre glass reinforcement up to 4.0 mm	double layer carrier film 86/52 in 0.125 mm
Thermal Properties*			
Thermal resistance R_{th}	K/W	1.2	1.2
Thermal conductivity λ	W/mK	2.0	2.0
Electrical Properties**			
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0	6.0
Volume resistivity	Ωm	2.2×10^{11}	2.8×10^{11}
Dielectric loss factor $\tan \delta$		1.0×10^{-3}	1.0×10^{-3}
Dielectric constant ϵ_r		3.6	2.5
Mechanical Properties			
Hardness	Shore 00	30 - 45	30 - 45
Young 's modulus	N/cm ²	58	160
Physical Properties			
Application temperature	°C	-40 to +180	-40 to +180
Density	g/cm ³	1.65	1.95
Total mass loss (TML)	Ma.-%	< 0.44	< 0.44
Flame rating	UL-94	V-0	V-0
Possible thickness	mm	0.5 - 5.0	0.5 - 5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

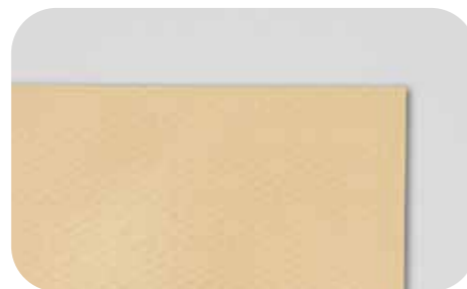
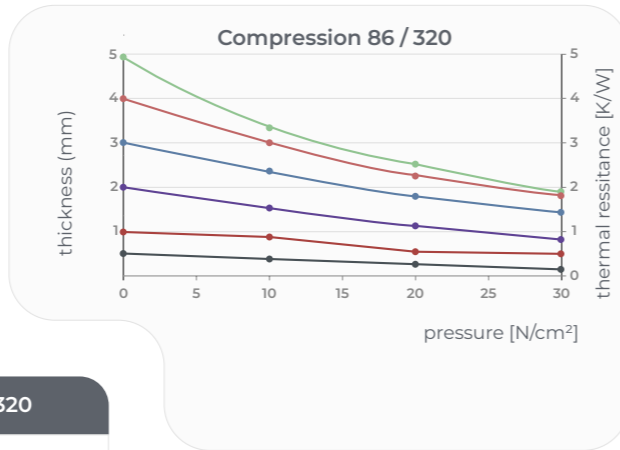
Properties	Unit	86 / 235	86 / 238
Colour		yellow	pink / yellow
Assembly		single layer, fibre glass reinforcement up to 2.0 mm	double layer carrier film 86/52 in 0.125 mm
Thermal Properties*			
Thermal resistance R_{th}	K/W	1.2	1.2
Thermal conductivity λ	W/mK	2.0	2.0
Electrical Properties**			
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0	6.0
Volume resistivity	Ωm	1.7×10^{11}	4.7×10^{11}
Dielectric loss factor $\tan \delta$		2.0×10^{-2}	1.0×10^{-3}
Dielectric constant ϵ_r		3.7	1.9
Mechanical Properties			
Hardness	Shore 00	25 - 45	25 - 45
Young 's modulus	N/cm ²	32	122
Physical Properties			
Application temperature	°C	-40 to +200	-40 to +200
Density	g/cm ³	1.65	1.65
Total mass loss (TML)	Ma.-%	< 0.10	< 0.05
Flame rating	UL-94	V-0	V-0
Possible thickness	mm	0.5 - 5.0	0.5 - 5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

86 / 320 Silicone Gap Pad

Benefits

- Good compromise between softness and thermal conductivity
- Very soft to compensate mechanical impacts like vibrations
- Elastic behavior



! At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

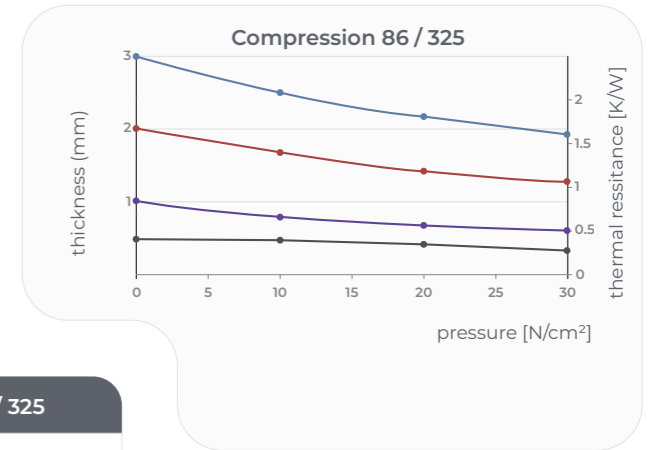
Properties	Unit	86 / 320
Colour		yellow
Assembly		single layer, fibreglass reinforcement up to 1.5 mm
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.0
Thermal conductivity λ	W/mK	2.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	5.0
Volume resistivity	Ωm	6.8×10^{11}
Dielectric loss factor $\tan \delta$		2.9×10^{-2}
Dielectric constant ϵ_r		3.4
Mechanical Properties*		
Hardness	Shore 00	25 - 38
Young´s modulus	N/cm ²	32
Physical Properties		
Application temperature	°C	-40 to +180
Density	g/cm ³	1.69
Total mass loss (TML)	Ma.-%	< 0.46
Possible thickness	mm	1.0 - 5.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

86 / 325 Silicone Gap Pad

Benefits

- Good compromise between softness and thermal conductivity
- Very soft to compensate mechanical impacts like vibrations
- Elastic behavior



! At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

Properties	Unit	86 / 325
Colour		mint
Assembly		single layer, fibreglass reinforcement up to 1.0 mm
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.82
Thermal conductivity λ	W/mK	3.0
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0
Volume resistivity	Ωm	8.5×10^{10}
Dielectric loss factor $\tan \delta$		1.5×10^{-1}
Dielectric constant ϵ_r		3.8
Mechanical Properties*		
Hardness	Shore 00	35 - 50
Young´s modulus	N/cm ²	64
Physical Properties		
Application temperature	°C	-40 to +180
Density	g/cm ³	1.95
Total mass loss (TML)	Ma.-%	< 0.35
Flame rating	UL-94	V - 0
Possible thickness	mm	0.5 - 4.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm

POLARIS 3000

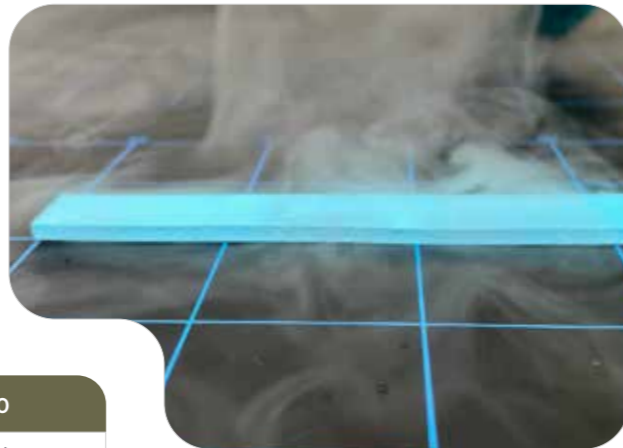
Silicone Gap Pad

Benefits

- Good compromise between softness and thermal conductivity
- Outstanding temperature stability
- Elastic behavior
- suitable for military and aerospace applications

Properties	Unit	3000
Colour		turquoise
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.82
Thermal conductivity λ	W/mK	3.0
Thermal impedance	mm ² /W	328
	kin ² /W	0.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	7.0
Mechanical Properties*		
Hardness	Shore 00	50-80
Physical Properties		
Application temperature	°C	-90 to +200
Density	g/cm ³	1.87
Flame rating	UL-94	VO***
Possible thickness	mm	0.5-4.0***

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm *** expected



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PRELIMINARY DATA SHEET

SOFTTHERM® 3500

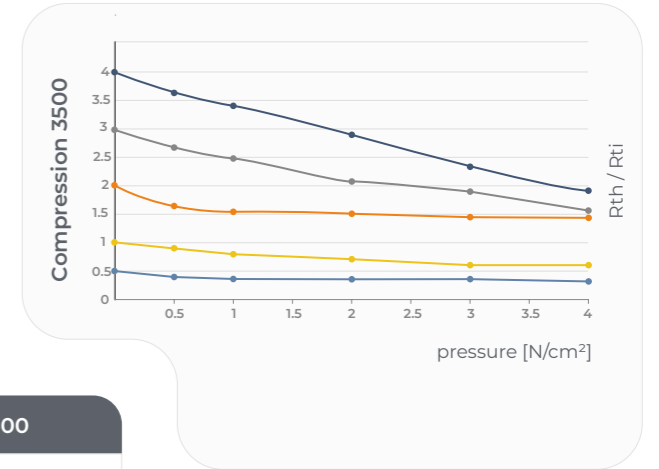
Silicone Gap Pad

Benefits

- Low thermal resistance
- Good price performance ratio
- Elastic behavior

Properties	Unit	3500
Colour		azure
Assembly		single layer
Thermal Properties*		
Thermal resistance R_{th}	K/W	0,82
Thermal conductivity λ	W/mK	3.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	5.0
Volume resistivity	Ωm	8.1×10^{10}
Dielectric loss factor $\tan \delta$		0.3
Dielectric constant ϵ_r		3.3
Mechanical Properties*		
Hardness	Shore 00	45 - 65
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	2.9
Total mass loss (TML)	Ma.-%	< 0.1
Flame rating	UL-94	V-0
Possible thickness	mm	1.0-4.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm



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86 / 450

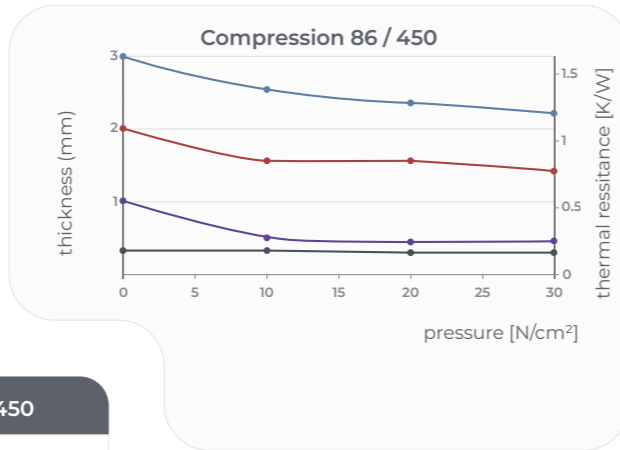
Silicone Gap Pad

Benefits

- Low thermal resistance
- High mechanical stability
- Elastic behavior

Properties	Unit	86 / 450
Colour		brown
Assembly		single layer
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.54
Thermal conductivity λ	W/mK	4.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	5.0
Volume resistivity	Ωm	3.6×10^{12}
Dielectric loss factor $\tan \delta$		3.0×10^{-3}
Dielectric constant ϵ_r		2.5
Mechanical Properties*		
Hardness	Shore 00	65 - 75
Young's modulus	N/cm ²	95
Physical Properties		
Application temperature	°C	-40 to +180
Density	g/cm ³	1.32
Total mass loss (TML)	Ma.-%	< 0.4
Flame rating	UL-94	V-0
Possible thickness	mm	0.5 - 4.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm



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86 / 525

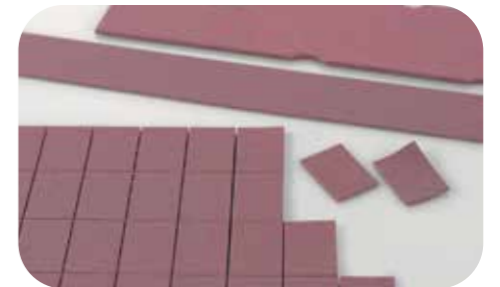
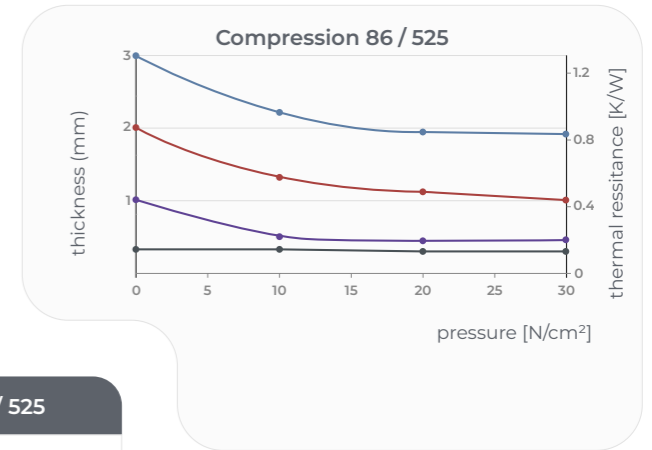
Silicone Gap Pad

Benefits

- Low thermal resistance
- High compensation of surface roughness
- Plastic behavior
- Non sticky, available with adhesive coating

Properties	Unit	86 / 525
Colour		violet
Assembly		single layer
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.44
Thermal conductivity λ	W/mK	5.5
Electrical Properties**		
Dielectric breakdown voltage $U_{d,ac}$	kV	1.25
Volume resistivity	Ωm	1.6×10^{13}
Dielectric loss factor $\tan \delta$		1.0×10^{-3}
Dielectric constant ϵ_r		2.7
Mechanical Properties*		
Hardness	Shore 00	50 - 65
Young's modulus	N/cm ²	99
Physical Properties		
Application temperature	°C	-40 to +180
Density	g/cm ³	1.18
Total mass loss (TML)	Ma.-%	< 0.35
Flame rating	UL-94	V-0
Possible thickness	mm	0.5 - 3.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm



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SOFTTHERM® 6000

Silicone Gap Pad

Benefits

- High thermal conductivity
- High electrical insulating
- Elastic



Properties	Unit	6000
Colour		pink
Assembly		silicone
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.41
Thermal conductivity λ	W/mK	6.0
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	4.0
Mechanical Properties		
Hardness	Shore 00	55-75
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	3.18
Total mass loss (TML)	Ma.-%	< 0.08
Flame rating	UL-94	V-0
Possible thickness	mm	0.8-3.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm



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U 110

Silicone free Gap Pad

Benefits

- high electrical insulating
- elastic
- Silicone free



Properties	Unit	U 110
Colour		brown
Basic material		silicone free
Thermal Properties*		
Thermal resistance R_{th}	K/W	1.2
Thermal conductivity λ	W/mK	2.0
Electrical Properties**		
Dielectric breakdown voltage $U_{d,AC}$	kV	8.0
Mechanical Properties		
Hardness	Shore 00	60-75
Physical Properties		
Application temperature***	°C	-40 to +110
Density	g/cm ³	1.87
Flame rating	UL-94	V-0
Possible thickness	mm	0.5-2.0

* Measured @ thickness 1 mm ** Measured @ thickness 0.5 mm
*** may cause increase in hardness



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Cost effective standard solutions

Thermally conductive films (KERATHERM®) are highly thermally conductive and electrically insulating elastomers based on silicone or polyurethane. Due to their low layer thickness of 100 to 500 µm, these materials are particularly suitable for generating efficient heat transfer from the heat source (e.g. semiconductor) to the heat sink (e.g. heat sink), especially with

low component tolerances. The simultaneously very high electrical insulation strength prevents electrical breakdowns and flashovers. To increase the mechanical stability, most of the films are also available with a glass fiber reinforcement; in addition, a one-sided adhesive coating can be applied.

Benefits

- Smooth surface
- Very good thermal properties even at low contact pressure
- Low hardness
- High self-adhesion
- High temperature stability

Film Options

- Optional single-sided adhesive coating
- Special thicknesses available
- Can be supplied on roll or already punched
- Fibreglass reinforcement available

used in...



Airplanes



Electrical Cars



Multi-media



Cell phones



Power tools

Applications

- Power supplies
- Automotive
- White goods
- Industrial applications
- Power converters

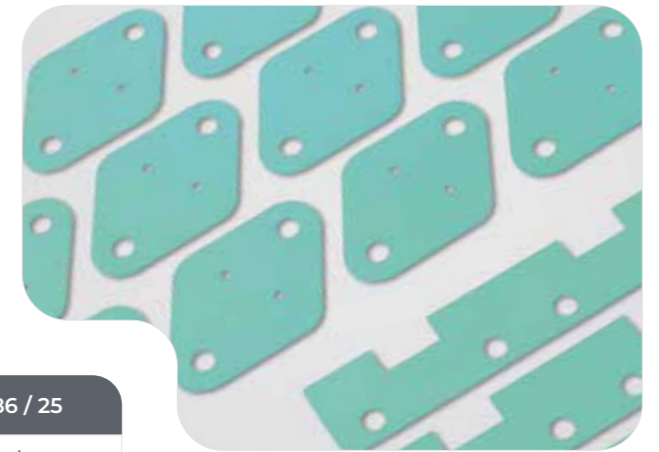
Properties

- Thermally conductive and electrically insulating at the same time
- Usage for low component tolerances and gap dimensions in the range of 0.1 to 0.5 mm
- Different polymer base possible

86 / 25 KERATHERM® mint

Benefits

- high thermal conductivity
- high electrical isolation
- easy handling
- optional available with adhesive coating



Properties	Unit	86 / 25
Colour		mint
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.225
Thermal conductivity λ	W/mK	2.5
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	3.5
Volume resistivity	Ωm	$1,5 \times 10^{11}$
Dielectric loss factor $\tan\delta$		8×10^{-3}
Dielectric constant ϵ_r		1,9
Mechanical Properties		
Hardness	Shore A	60 - 75
Tensile strength	N/mm ²	tbd
Elongation	%	tbd
Physical Properties		
Application temperature	°C	-60 to +200
Density	g/cm ³	2.37
Possible thickness	mm	0.225

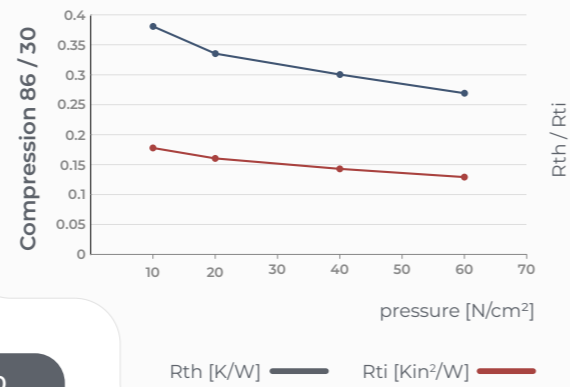
* Measured @ thickness 0.225 mm

✓ Optional available with onside adhesive coating 86/25 K

86 / 30 KERATHERM® white

Benefits

- Good thermal conductivity
- Available with adhesive coating
- Reinforcement with fiberglass possible



Properties	Unit	86 / 30
Colour		white
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.22
Thermal conductivity λ	W/mK	2.5
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	1.5
Volume resistivity	Ωm	2.5×10^{11}
Dielectric loss factor $\tan\delta$		2.2×10^{-2}
Dielectric constant ϵ_r		3.0
Mechanical Properties		
Hardness	Shore A	70-80
Tensile strength	N/mm²	1.5
Elongation	%	31
Physical Properties		
Application temperature	°C	-60 to +250
Density	g/cm³	2.33
Flame rating	UL-94	V-0
Possible thickness	mm	0.125-0.5

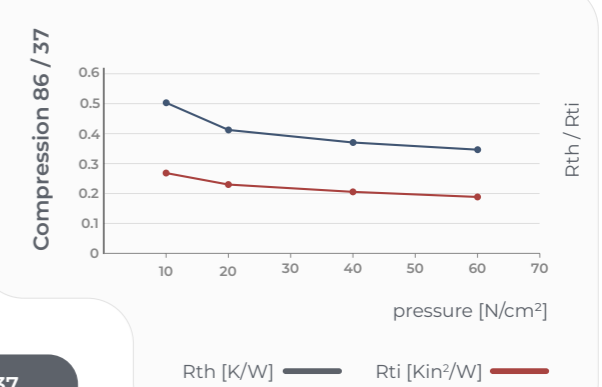
Options	Properties	Unit	86 / 10	86 / 20	86 / 40
	Film structure		with fibreglass	with fibreglass and adh. coating	with adh. coating
	Overall thickness	mm	0.225	0.250	0.250
	Tensile strength	N/mm²	7.5	7.5	1.5
	Breakdown voltage $U_{d,ac}$ *	kV	1.5	1.5	1.5
	Thermal resistance	K/W	0.250	0.300	0.265

* Measured @ thickness 0.225 mm

86 / 37 KERATHERM® green

Benefits

- High electrical insulation
- Cost effective solution
- Available with adhesive coating
- Reinforcement with fiberglass possible



Properties	Unit	86 / 37
Colour		green
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.32
Thermal conductivity λ	W/mK	1.8
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	8.0
Volume resistivity	Ωm	2.5×10^{11}
Dielectric loss factor $\tan\delta$		6.0×10^{-3}
Dielectric constant ϵ_r		2.9
Mechanical Properties		
Hardness	Shore A	65-75
Tensile strength	N/mm²	2.0
Elongation	%	75
Physical Properties		
Application temperature	°C	-60 to +250
Density	g/cm³	2.29
Flame rating	UL-94	V-0
Possible thickness	mm	0.125-0.5

Options	Properties	Unit	86 / 17	86 / 27	86 / 47
	Film structure		with fibreglass	with fibreglass and adh. coating	with adh. coating
	Overall thickness	mm	0.225	0.250	0.250
	Tensile strength	N/mm²	7.5	7.5	2.0
	Breakdown voltage $U_{d,ac}$ *	kV	6.0	6.0	8.0
	Thermal resistance	K/W	0.39	0.55	0.50

* Measured @ thickness 0.225 mm

86 / 50 KERATHERM® pink

Benefits

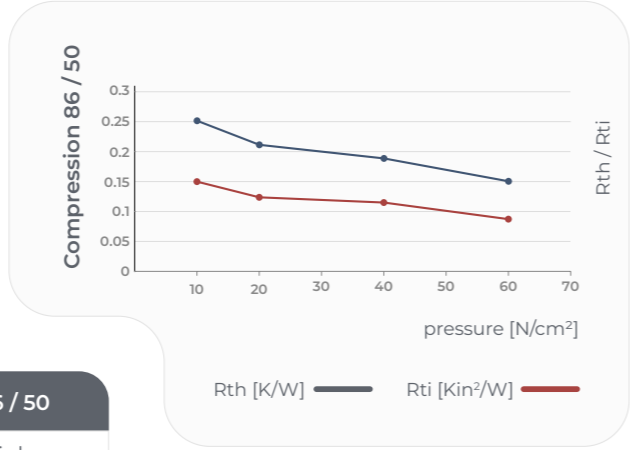
- High thermal conductivity
- Available with adhesive coating
- Reinforcement with fiberglass possible

Properties	Unit	86 / 50
Colour		pink
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.16
Thermal conductivity λ	W/mK	3.5
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	1.5
Volume resistivity	Ωm	1.3×10^{14}
Dielectric loss factor $\tan\delta$		6.7×10^{-2}
Dielectric constant ϵ_r		2.3
Mechanical Properties		
Hardness	Shore A	70 - 80
Tensile strength	N/mm ²	1.3
Elongation	%	25
Physical Properties		
Application temperature	°C	-60 to +250
Density	g/cm ³	1.97
Flame rating	UL-94	V-0
Possible thickness	mm	0.125 - 0.5

Options

Properties	Unit	86 / 51	86 / 52	86 / 53
Film structure		with adh. coating	with fibreglass	with fibreglass and adh. coating
Overall thickness	mm	0.250	0.225	0.250
Tensile strength	N/mm ²	1.3	10.0	10.0
Breakdown voltage $U_{d,ac}$ *	kV	1.5	1.5	1.5
Thermal resistance	K/W	0.26	0.22	0.27

* Measured @ thickness 0.225 mm



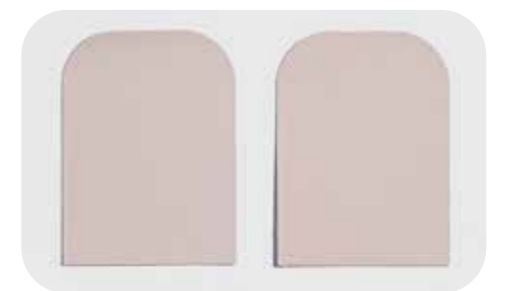
L 86 / 50 – PEEK KERATHERM®

Benefits

- Double layer material
- High electrical insulation
- Higher thermal performance in comparison to comparable hybrid films
- No removal of a carrier film require

Properties	Unit	
Carrier material		PEEK® – Folie
Material thickness	µm	25
Compression material		Keratherm 86/50
Thickness	µm	225
Laminate construction		86/50-PEEK®-Folie
Thickness	µm	250
Thermal conductivity*	W/mK	1.1
Thermal resistance R_{th}	K/W	0.51
Dielectric breakdown	KV/mm	8.0
Hardness	Shore A	70 - 80
Application temperature	°C	-40° to +250°
Tensile strenght	N/mm ²	8

* Measured @ thickness 0.25 mm



Customized, KERATHERM® Hybrid film with PEEK® carrier film

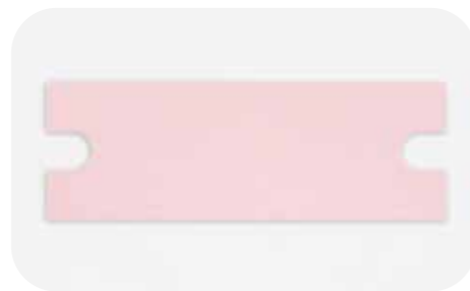
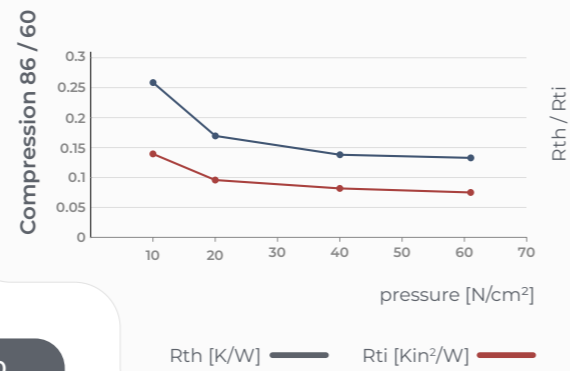
86 / 60 KERATHERM® pink

Benefits

- High thermal conductivity
- High electrical insulating
- Available with adhesive coating

Properties	Unit	86 / 60
Colour		pink
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.14
Thermal conductivity λ	W/mK	4.5
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	5.0
Volume resistivity	Ωm	$>6.0 \times 10^{12}$
Dielectric loss factor $\tan \delta$		0.0
Dielectric constant ϵ_r		1.5
Mechanical Properties		
Hardness	Shore A	45 - 60
Tensile strength	N/mm ²	0.5
Elongation	%	25
Physical Properties		
Application temperature	°C	-60 to +200
Density	g/cm ³	1.38
Flame rating	UL-94	V-0
Possible thickness	mm	0.25-0.5

* Measured @ thickness 0.25mm



✓ Optional available with onside adhesive coating **86/60 K**

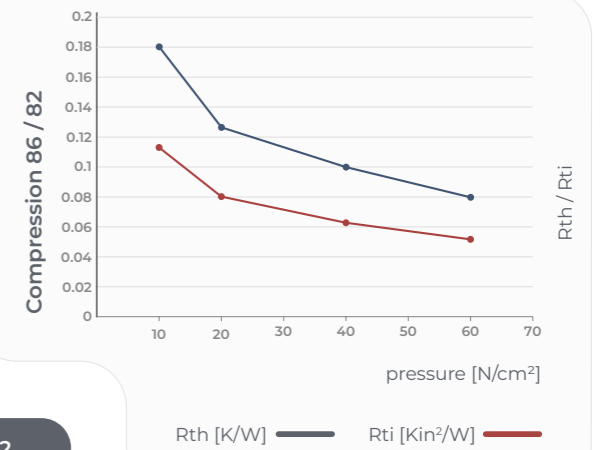
86 / 82 KERATHERM® red

Benefits

- High thermal conductivity
- High electrical insulating
- Available with adhesive coating

Properties	Unit	86 / 82
Colour		red
Assembly		fibreglass reinforcement
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.09
Thermal conductivity λ	W/mK	6.5
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	1.0
Volume resistivity	Ωm	2.0×10^{14}
Dielectric loss factor $\tan \delta$		1.4×10^{-3}
Dielectric constant ϵ_r		2.4
Mechanical Properties		
Hardness	Shore A	60-70
Tensile strength	N/mm ²	13.0
Elongation	%	2
Physical Properties		
Application temperature	°C	-40 to +200
Density	g/cm ³	1.23
Flame rating	UL-94	V-0
Possible thickness	mm	0.25-0.3

* Measured @ thickness 0.25mm



✓ Optional available with onside adhesive coating **86/82 K**

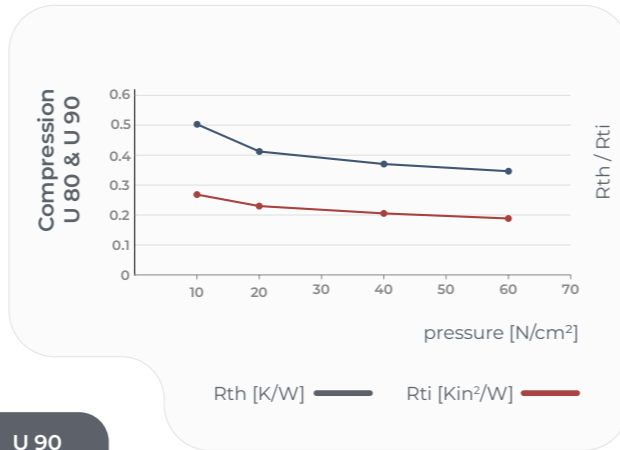
U 80 & U 90 KERATHERM® silicone free Thermal Tape

Benefits

- Silicone free (polyurethane)
- Very high thermal performance
- Good ratio between thermal performance and electrical isolation
- Softening effect for an additional increase in heat output
- Non sticky, available with adhesive coating

Properties	Unit	U 80	U 90
Colour		blue	light blue
Thermal Properties			
Thermal resistance R_{th}	K/W	0.2*	0.082**
Thermal conductivity λ	W/mK	1.8*	6.0**
Electrical Properties			
Dielectric breakdown voltage $U_{d,AC}$	kV	4.0*	4.0**
Volume resistivity	Ωm	1.4×10^{14} *	2.0×10^{11} **
Dielectric loss factor $\tan \delta$		1.3×10^{-2} *	1.4×10^{-2} **
Dielectric constant ϵ_r		3.2*	3.1**
Mechanical Properties			
Hardness	Shore A	80 - 90	70 - 85
Tensile strength	N/mm ²	3.0	2.0
Elongation	%	130	150
Physical Properties			
Application temperature	°C	-40 to +125	-40 to +125
Density	g/cm ³	2.26	1.46
Flame rating	UL-94	V-0	V-0
Possible thickness	mm	0.15-0.3	0.1-0.3

* Measured @ thickness 0.15 mm ** Measured @ thickness 0.2 mm



✓ Optional available with adhesive coating **U 80K / U 90K**

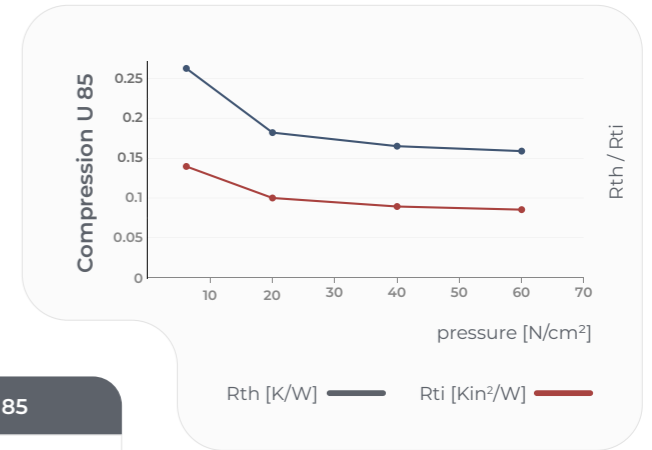
U 85 KERATHERM® silicone free Thermal Tape

Benefits

- Silicone free (Epoxy)
- High temperature stability
- Good ratio between thermal performance and electrical isolation
- Non sticky, available with adhesive coating

Properties	Unit	U 85
Colour		light blue
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.165
Thermal conductivity λ	W/mK	3.0
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0
Volume resistivity	Ωm	4.1×10^9
Dielectric loss factor $\tan \delta$		2.6×10^{-2}
Dielectric constant ϵ_r		2.0
Mechanical Properties*		
Hardness	Shore A	70 - 85
Tensile strength	N/mm ²	1.0
Elongation	%	>50
Physical Properties		
Application temperature	°C	-40 to +150
Density	g/cm ³	1.44
Flame rating	UL-94	V-0
Possible thickness	mm	0.2

* Measured @ thickness 0.2 mm



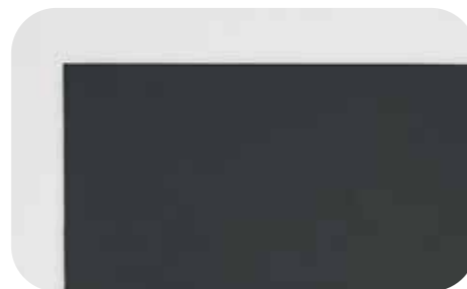
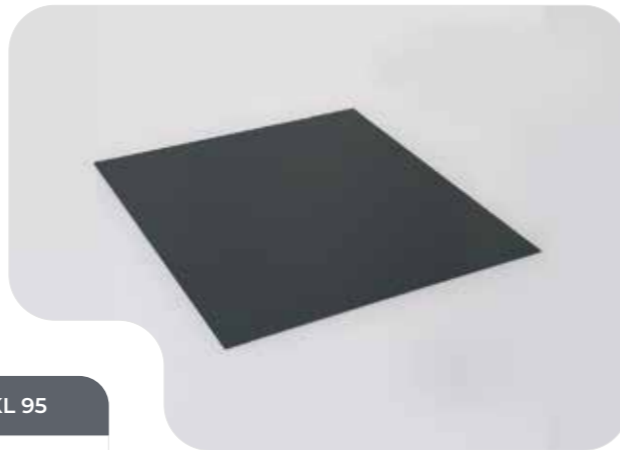
✓ Optional available with adhesive coating **U 85K**

KL 95

KERATHERM® thermally conductive adhesive film

Benefits

- High thermal conductivity
- High adhesive strength
- Good adhesion to various surfaces
- low thickness



Properties	Unit	KL 95
Colour		grey
Basic material		Filled Acrylic Polymer
Thermal Properties*		
Thermal conductivity λ^{**}	W/mK	1.3
Thermal resistance R_{th}	K/W	0.32
Electrical Properties*		
Dielectric breakdown voltage $U_{d,AC}$	kV	2.0
Volume resistivity	Ωm	2.0×10^{11}
Dielectric loss factor $\tan \delta$		24×10^{-1}
Dielectric constant ϵ_r		1.7
Mechanical Properties		
Hardness	Shore A	60
Tensile shear strength†	N/cm ²	> 6.5
Tensile shear strength† (Temperature aging)	1h/65°C 24h/65°C 72h/65°C	26.90 34.30 48.80
Physical Properties		
Adhesion*** (bonding strength)	Nmm	> 0.5
Tack*** (surface Adhesiveness)	mm	> 1.0
Density	g/cm ³	2.24
Application temperature***	°C	-40 to +100
Flame rating	UL-94	V-0
Possible thickness	mm	0.18 - 0.3

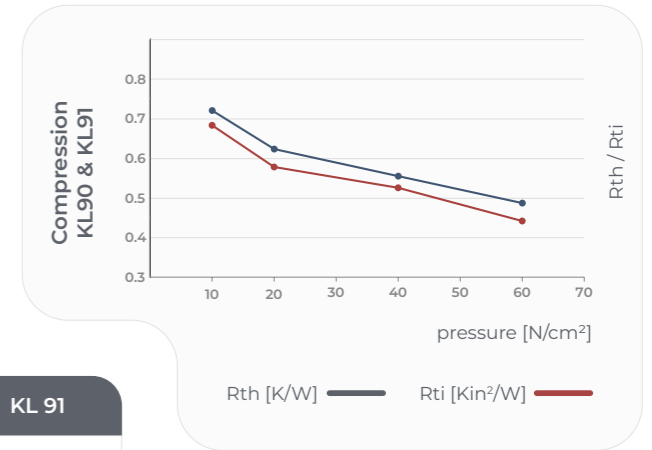
* Measured @ thickness 0.18 mm
 ** Tensile shear strength Alu/Foil/Alu – 25x25 mm²(outsourcing – 48h/RT);
 *** used measurement – Texture Analyser (TA.XT-plus)

KL 90 & KL 91

KERATHERM® thermally conductive adhesive film

Benefits

- High thermal conductivity
- High adhesive strength
- Good adhesion to various surfaces
- Reinforcement with fiberglass possible



Properties	Unit	KL 90	KL 91
Colour		black	black
Basic material		acrylate	acrylate
Reinforcement (fibreglass)		without	with
Thermal Properties*			
Thermal resistance R_{th}	K/W	0.52	0.55
Thermal conductivity λ	W/mK	1.40	1.35
Electrical Properties*			
Dielectric breakdown voltage $U_{d,AC}$	kV	6.0	6.0
Volume resistivity	Ωm	2.6×10^4	2.6×10^4
Dielectric loss factor $\tan \delta$		3.1×10^{-1}	3.1×10^{-1}
Dielectric constant ϵ_r		18.5	18.5
Mechanical Properties			
Hardness	Shore A	45	59
Tensile strength	N/mm ²	0.3	11.3
Physical Properties			
Application temperature	°C	-40 to +125	-40 to +125
Density	g/cm ³	1.98	1.87
Total mass loss (TML)	Ma.-%	< 0.15	< 0.15
Flame rating	UL-94	V-0	V-0
Possible thickness	mm	0.3-0.5	0.3

* Measured @ thickness 0.3 mm



Ceramic filled double-sided adhesive film - with or without fibreglass! KL 90 and KL 91 are double sided adhesive films. They have an excellent, adhesive strength with high thermal conductivities and very good insulation characteristics at the same time.

Low thermal contact resistances can be achieved with adhesive strength on different surfaces.

No mechanical fixation with clips or screws needed.

Due to the soft surface finish, tolerances can be compensated very well. Light weight, easy handling and high elasticity are further advantages.

Adhesive Films

Specific film characteristics

Specific film characteristics	Unit	KL 90	KL 91
		(without fibreglass)	(with fibreglass)
Testing the reflow stability 10s/270°C		passed	passed
	µm	300	300
Shelf Life	month	12	12
Application conditions	[pressure/ time]	N/cm ² /sec.	10/10
Tensile shear strength		N/cm ²	> 30
[25mmx25mm-adhesive area-180°		[DIN EN 1465]	
aluminum – adhesive film – aluminum]		[ASTM D 1002]	
Tensile shear strength	-20°C	N/cm ²	157.2
temperature-depending**	+20°C	[DIN EN 1465]	51.7
[25mmx25mm-adhesive area-180°	+60°C	[ASTM D 1002]	14.1
aluminum – adhesive film – aluminum]	+70°C		12.0
	+80°C		10.7
Tensile shear strength		N/cm ²	31.5
after vibration test (sinusoidal with temperature overlay at 60°C)			32.5
vibration 10–500 Hz; 50 s/m ² (5g) test cycle 24h (6h per axis) [1]			
Tensile shear strength		N/cm ²	32.1
after vibration test (sinusoidal at RT)			35.9
vibration 10–500 Hz; 100 s/m ² (10g) test cycle 24h (8h per axis) [2]			
Adhesion* (bonding strength)		Nmm	> 1.2
Tack* (surface adhesiveness)		mm	> 1.0
Peel strength [90° -on aluminum]		N/25mm	> 1.2
		3 [adhesive]	9 [adhesive]

Adhesive Coatings

1. Processing and handling instructions

When the basic rules of processing and handling are followed, KL 90, KL 91 and KL 95 double-sided adhesive films display very good processing characteristics. They enable to dispense with mechanical fastening aids such as staples, screws or rivets. In addition to the good thermal and dielectric properties, the adhesion and good plasticity enhance good processability.

2. Surface conditions

The surfaces must be dry and free of any impurities, (such as oil, fat, dust, paint coatings and possible solvent contamination). Condensation (e.g. when changing from cold to warm) must be avoided.

3. Cleaning the surfaces

Depending on the component's condition, its surface may need to be cleaned mechanically or chemically. Mechanical cleaning roughens the surface. Make sure that the surface roughness is not as deep as the adhesive tape's thickness. Chemical cleaning should be done with soft, clean cloths and solvents that are compatible with the material, such as alcohols, benzines, esters or ketones. These solvents' residues must not be left on the surfaces because they interfere with the tape's adhesion.

4. Adhesion

Naturally on plastics containing plasticizers and those of a nonpolar character, the bond is impaired. Besides appropriate adhesion tests on these materials, a chemical or physical surface treatment is, if necessary a prerequisite for improved bonding of the materials.

1. Processing temperatures and necessary transmission forces

The adhesive tapes processing temperature is between +18°C and +35°C with a relative air humidity of 50% – 70%. A different temperature or air humidity will change the initial strength (adhesion). Increased contact pressure improves the tape's adhesion on the surface of the component. For larger, flatter bonds, adhesion can be improved by using a pressure roller or a surface press (contact pressure about 10 – 15 N/cm²). The final, highest adhesive strength is reached about 24 to 72 hours after application. A moderate temperature treatment to a maximum of 80°C supports this process and shortens the time (dynamic cycle with 30 minutes hold time).

2. Protective sheets and application to the component

The KL 90, KL 91 and KL 95 adhesive films are covered with two different siliconized sheets. To apply the adhesive film, first the PP sheet must be peeled off the tape (re-lease lightly!). Then the adhesive tape (or also stamping) is pressed onto the surface to be adhered to (as described above). This can be followed by direct further processing or interim storage. For final assembly, the PETP protective sheet must be removed.

3. Storage

KL 90, KL 91 and KL 95 double-sided adhesive films must be stored at room temperature and normal humidity (room temp. = 18°C – 22°C; rel. humidity = 50% – 70%). Direct (effects of) sunlight or storage near heat sources must be absolutely avoided. To prevent pressure points, the rolls should be stored only vertically. It is recommended to test Therefore, it is recommended to test the adhesion before each use and application.

KP 97, 98, 99, 12 & 14 KERATHERM® Thermal Grease

Benefits

- Outstanding thermal performance
- Easy to apply
- Available in different packaging forms (syringe, cartridges, cans & hobbocks)
- Available as silicone and silicone free option
- Very low bond line thickness



Properties	Unit	97	98	99	12 <small>silicone free</small>	14 <small>silicone free</small>
Colour		white	grey	anthra- cite	silver	dark- grey
← softy/pasty →						
Thermal Properties*						
DeltaT	°C	≤1.6	≤1.4	≤1.2	≤1.2	≤1.2
Thermal conductivity λ**	W/mK	5.0	6.0	9.2	10.0	10.0
Electrical Properties*						
Electrical conductivity (according to DIN 51412-1)	pS/m	0	0	0	53	0
Mechanical Properties						
Measured thickness (+/-10%)	mm	0.025	0.025	0.025	0.025	0.025
Physical Properties						
Application temperature	°C	-60 to +200	-60 to +200	-60 to +200	-60 to +150	-60 to +150
Density	g/cm ³	2.1	2.2	1.9	1.4	2.2
Viscosity***	Pas	70-110	110-150	90-140	30-60	150-180
Total mass loss (TML)	Ma.-%	<1.3	<1.5	<0.80	<0.1	<0.25
Possible thickness	mm	← variable →				

* Measured @ thickness 0.025 mm ** reference value: old measurement method *** Shear rate 4.6s⁻¹ / 25°C

KERATHERM® Thermal Greases are ceramic-filled single component silicones with a high thermal conductivity.

The thermal grease KP 99 is a high-quality thermal grease. The homogeneous thixotropic grease shows a very good fluidity thanks to its low viscosity characteristics, which leads to a good surface adaptation. The silicone free thermal compound KP 12 & KP14 consists of synthetic, thermal polymers and is suitable for a fast and effective heat dissipation. The paste is particularly suitable for silicone sensitive application. If any separation of the filler materials becomes evident, the KP´s must be mixed thoroughly before use according to the corresponding processing instructions.

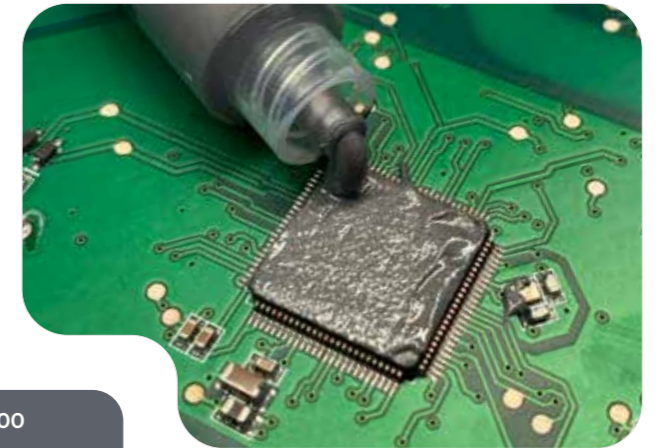
Special packing on request!

KP 100 KERATHERM® Thermal Grease

NEW
DATA SHEET

Benefits

- High thermal performance
- Easy to apply
- Available in different packaging forms (syringe, cartridges, cans & hobbocks)
- Outstanding long-term test results at power cycle test with Semiconductors
- Very low bond line thickness



Properties	Unit	100
Colour		grey
Thermal Properties*		
Thermal conductivity λ**	W/mK	5.0
DeltaT	°C	1.9
Mechanical Properties		
Measured thickness (+/-10%)	mm	0.025
Physical Properties		
Application temperature	°C	-60 to +200
Density	g/cm ³	1.4
Viscosity***	Pas	30-60

* Measured @ thickness 0.025 mm ** reference value: old measurement method *** Shear rate 4.6s⁻¹ / 25°C

KERATHERM® Thermal Greases are ceramic-filled single component silicones with a high thermal conductivity.

The thermal paste KP100 sets new standards in terms of cooling high-performance electronic components such as SiC MOSFETS. Due to its ultra-thin bond-line thickness of < 25 µm and its special filling, this thermal compound can lead to a massive improvement in terms of resistance to power cycle tests.

Special packing on request!

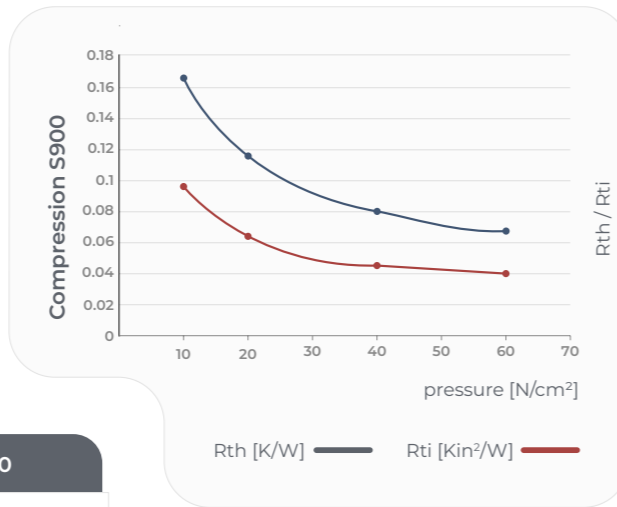
S 900 Interface Material

Benefits

- Outstanding thermal performance
- Heat spreading effect, perfect match for "Hot Spots"
- electrically conductive
- Non sticky, available with adhesive coating
- High temperature stability

Properties	Unit	S 900
Colour		black
Thermal Properties*		
Thermal resistance R_{th}	K/W	0.08
Thermal conductivity λ z (x / y)	W/mK	7.5 (>300)
Electrical Properties*		
Breakdown voltage $U_{d,AC}$	kV	conductive
Electrical resistance z (x / y)	$\Omega\mu\text{m}$	700 - 800 (7 - 9)
Mechanical Properties		
Hardness	Shore D	25 - 35
Tensile strength	N/mm ²	10.0
Elongation	%	5
Physical Properties		
Application temperature	°C	-40 to +500
Total mass loss (TML)	Ma.-%	0.01
Flame rating	UL-94	V - 0
Possible thickness	mm	0.15 - 0.29

* Measured @ thickness 0.29 mm



Graphite S 900 is a highly dense, natural graphite without binding material, which is rolled or pressed into films or plates.

S 900 has exceptional qualities and is therefore used particularly as a cost-effective alternative to conventional interface material. Especially, the anisotropy of the thermal properties (coupled with a possible weight saving of up to 30% compared to conventional materials made of copper or aluminum), makes the S 900 interesting for headspreader applications.

In addition, applications in vacuum or even at higher temperatures (400 °C) are possible. Graphite S 900 has no electrical insulation and can be customized and applied with an adhesive coating.

- ✓ Optional available with onside adhesive coating as **S 900K**

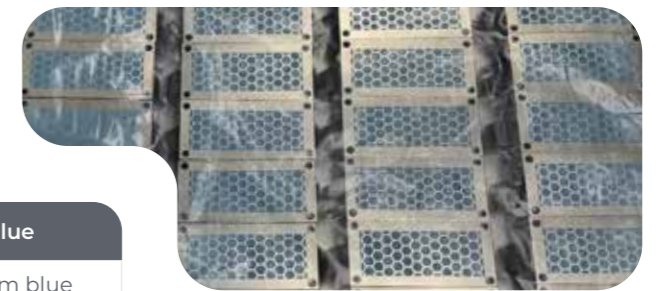
PCM 16125C KERATHERM®

Application

- Thyristors
- Desktop CPU 's
- IGBT units

Benefits

- Filling of smallest irregularities between the power module and heat sink
- Improves the contact between the surfaces and increases the heat transfer
- Good applicability in the form of screen and stencil printing
- Possibility to buy pre assembled parts
- Very low bond line thickness



Properties	Unit	Value
Colour		Titanium blue
Viscosity Brookfield K/P* <small>(Temperature dependent; dried area)</small>	Pas	400/creamy (@40°C) 200 (@50°C) 120 (@60°C) 80 (@80°C) 50 (@100°C)
Thermal conductivity λ	W/mK	>3.5
Dielectric breakdown E_d	kV	>1
Operating temperature	°C	-40 to +120
Softening interval	°C	52 - 54
Possible layer thickness	μm	50 - 250
Post-curing time (40°C @ 250 μm)**	h	18 - 24

* Sheare rate λ 4.6s⁻¹

** This time is valid for natural convection. If there is some kind of ventilation, the time curing time is lower

KERASORB® 2500 & 1500

EMI Absorbing Gap Pad

Application

- Base Station
- 5G Data Infrastructure
- Consumer electronics
- Autonomous vehicle
- Radar sensors

Benefits

- High thermal conductivity
- High EMI suppression @ frequencies up to 77 GHz
- Electromagnetic properties independent from layer thickness
- High electrical isolation
- Elastic



Properties	Unit	2500	1500
Colour		mint	orange
Thermal Properties*			
Thermal conductivity λ	W/mK	2.5	1.5
Electrical Properties**			
Dielectric breakdown voltage $U_{d,AC}$ ***	kV	5.0	5.0
EMI Attenuation**	dB	≥ 40	≥ 40
Mechanical Properties			
Hardness	Shore 00	35 - 50	30 - 45

* Measured @ thickness 1 mm ** Measured @ 45 & 77 GHz *** Measured uncompressed

The new series KERASORB is a HYBRID material of THERMAL & EMI ABSORBER. This means, besides the classic properties of a TIM (thermal interface material) that is used between the heat source (electronic device) & heat sink, this new material also suppresses unwanted energy coupling, resonances or surface currents which cause board level EMI issues.

The Kerabsorb 2500 is characterized by its high thermal conductivity and high level of EMI suppression at very high frequencies up to 77 GHz.

! At maximum pressure, Gap Pads (SOFTTHERM® Films) should not be compressed beyond 30% of the original thickness. In case the material should be compressed more than 30%, the SOFTTHERM® material may leak out.

Good to know... KERATHERM® Films

KERATHERM® Films are mainly resistant to water, oils and their mixtures, organic solvents and chlorinated hydrocarbons, as well as the cleaning agents used to degrease and wash heat sinks, housings and printed circuit boards.

KERATHERM® products involve none of the substances specified on the VDA list of declarable substances. KERATHERM® products contain no asbestos, lead, mercury, chromium-6, cadmium and/or halogenated hydrocarbons.

These materials merely cause swelling of exposed edges of the heat-conducting film, in which the degree of swelling depends on the contact period and the type of solvent applied.

All listed products in our catalog meet the requirements of RoHS and Reach!

After dry-out, the exposed edges return to their original state with no change in thermal or electrical properties. Due to the short contact times involved, KERATHERM® may be exposed to the conventional baths used in soldering processes.

Delivery form

Besides a large number of standard shapes (TO, TIP, DO or other power housing shapes), we can supply punch parts in customized shapes of almost any arbitrary size based on

customer drawings (max. 400x400 mm). Rolls can be supplied in film widths from 15 mm up to 500 mm. The Gap Pads (SOFTTHERM® Films) are supplied as sheets.

Tolerances

KERATHERM® Thermal Conductive Tapes: In terms of geometry, as well as position and shape of the parts or holes to be punched or relevant recesses and outlines, the tolerances are fixed at a minimum of 0.10 mm in accordance with DIN ISO 2768-m. With regard to the thickness, a tolerance of +/- 10% of the total thickness is possible.

KERATHERM® Gap Pads (SOFTTHERM® Films): the geometry, as well as position and shape of the parts are also fixed at a minimum of 0.10 mm in accordance with DIN ISO 2768-c. For holes or relevant recesses and outlines the following table applies.

KERATHERM® Graphit tolerances according DIN ISO 2768-c.

thickness	tolerance thickness	tolerance holes
up to 1.000 mm	± 0.100 mm	± 0.500 mm
up to 2.000 mm	± 0.200 mm	± 1.000 mm
up to 3.000 mm	± 0.300 mm	± 1.500 mm
up to 4.000 mm	± 0.400 mm	± 2.000 mm
up to 5.000 mm	± 0.500 mm	± 2.500 mm

KERATHERM® Test Methods

Batchwise determination of thermal properties

An equi-area measurement sample (4 cm² base area) is placed between a heatable upper die and a cooled lower die. The lower die is pressed against the upper one by means of a pneumatic pressure cylinder. The pressure dependence of the thermal resistance of the samples is derived from the variation in contact pressure. After approx.

20 minutes, the resultant temperature gradient above the sample is determined via Pt-100 sensors. The thermal resistance (R_{th}) and the thermal conductivity (λ) are calculated on the basis of this temperature gradient, the heating power passed through the sample, and the sample geometry.

Storage conditions and preservation instructions for KERATHERM® products

For more information about the handling and storage conditions contact our team or our sales partner.

Determination of electrical properties

The electrical insulation effect of the heat-conducting films is characterized by their dielectric strength. The higher the breakdown voltage, the better the insulation behavior. Measurements are performed with an AC high-voltage detector.

Determination of mechanical properties

State-of-the-art equipment and measurement devices facilitate the batch-wise determination of tensile strength and elongation of the films. In addition to this, the peel strength of adhesive coated materials is determined on the basis of the "Finat Test Method No.1" (180°).

Determination of flame rating

Most of the available KERATHERM® products have been certified and categorized into classes with regard to their inflammability by the American institute "Underwriters Laboratories Inc." (UL). In addition to this, the company KERAFOLE® endeavours to test its products on the basis of the latest findings in research and development.

YOUNGS MODULUS studies

KERAFOL® analyses the behavior of flexible films under pressure, using the method described in ASTM D 575-91, to determine the so-called YOUNG'S MODULUS. The sample geometry of the individual

film types is 30x30 mm at 2.5 mm thickness, and pressure is applied with a constant traverse path of 1 mm/min (0.04 in/min). The pressure dependence of the films is shown on the graphs.

Further information regarding the UL identifiers of KERAFOL® products is available on the UL website. Visit <http://www.ul.com> and select the category "Online Certifications Directory". From there you can search for the KERAFOL® file under the following file number:

QMFZ2E140693: Plastics Component. This category contains all KERAFOL® products.

discription	unit	test method	
Thermal resistance R_{th} *	K/W	KERAFOLE® - test method	
Thermal conductivity*	W/mK	KERAFOLE® - test method	ASTM D 5470
Breakdown voltage (U _d ; ac)	kV	IEC 2431+2	ASTM D 149
Dielectric breakdown (E _d ; ac)	kV/mm	IEC 2431+2	ASTM D 149
Volume resistivity	Ω m	DIN 53483-3	ASTM D 257
Dielectric loss factor $\tan \delta$		DIN 53483	ASTM D 150
Dielectric constant ϵ_r		DIN 53483	ASTM D 150
Electrical conductivity	pS/m	DIN 51412-1	
Measured thickness	mm	DIN 53370	ASTM E 252
Tensile strength	N/mm ²	DIN EN ISO 527-3	ASTM D 412a
Elongation	%	DIN EN ISO 527-3	ASTM D 412a
Hardness	Shore (A,D) Shore 00	DIN 53505	ASTM D 2240
Compressibility**	mm	DIN ISO 815-1	ASTM D 395
Youngs Modulus**	N/cm ²	-	ASTM D 575
Flame rating	UL	UL 94 / E140693	UL 94 / E140693
Total mass loss (TML)	Ma.-%		ASTM E 595

Modified test geometry

* Thermal conductivity λ , thermal resistance R_{th} and thermal impedance R_{ti} (4 cm²)
 ** Compressibility and „Young´s Modulus“ (3.0 cm x 3.0 cm = 9.0 cm²)

Conversion

Shape: 1000 mil = 1 inch (1") = 25.4 cm = 25.4 mm
 Area: 1 inch² = 6.45 cm² = 645 mm²
 Pressure: 100 N/cm² = 1MPa = 10 bar = 145.037 psi

Note

Disclaimer of Warranties and Limitation of Liability

The specifications provided in this data sheet do not constitute a guarantee or warranty of specific product properties („quality guarantee“). These specifications are derived from our standardized testing procedures conducted under controlled laboratory conditions and are intended to describe the typical properties of the products as expected under standard applications. Variations may occur depending on the specific application. Accordingly, it is the responsibility of the customer to test and evaluate the products for their intended use, and adjustments to the application may be required.

The customer assumes full responsibility for the safety and functionality of their applications in which these products are integrated. Appropriate safety measures must be implemented to prevent bodily injury, fire, or other damages resulting from product defects. The customer is also responsible for ensuring that the design of their application complies with all applicable laws, regulations, codes, and standards. Unless expressly authorized by us in writing, our products must not be used in any application where product failure or the consequences thereof could reasonably be expected to result in personal injury or harm. We make no representations, warranties, or assurances regarding the accuracy, completeness, or suitability of the information contained herein, including, without limitation, any warranty of non-infringement of third-party intellectual property rights.

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Products may contain substances subject to regulatory labeling requirements; such information is provided in the corresponding safety data sheets. This document supersedes all prior information and may be updated or replaced at our discretion. We reserve the right to make changes to this document without notice.

12-2024



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Customized solutions

We are looking forward to receiving your inquiry!

KERAFOL® products are applied in vehicle electronics, telecommunications, aerospace, computers and the semi-conductor industry – in fact, in all areas in which generated heat has to be dissipated from sensitive components to the heat sink.

Discover our wide range of products and take advantage of the diverse application possibilities!



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